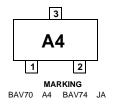


BAV70/74





Connection Diagram



Small Signal Diode

Absolute Maximum Ratings * T_A = 25°C unless otherwise noted

| Symbol | Parameter | Value | Units | |
|--------------------|--|----------------|-------------|--------|
| V _{RRM} | Maximum Repetitive Reverse Voltage | BAV70 BAV74 | 70 50 | V V |
| I _{F(AV)} | Average Rectified Forward Current | | 200 | mA |
| I _{FSM} | Non-repetitive Peak Forward Surge Current Pulse Width = 1.0 second Pulse Width = 1.0 microsecond | | 1.0 2.0 | A A |
| T _{STG} | Storage Temperature Range | | -55 to +150 | °C |
| T _J | Operating Junction Temperature | | 150 | °C |

^{*} These ratings are limiting values above which the serviceability of the diode may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
 These are steady limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics

| Symbol | Parameter | Value | Units |
|------------------|---|-------|-------|
| P _D | Power Dissipation | 350 | mW |
| R _{eJA} | Thermal Resistance, Junction to Ambient | 357 | °C/W |

Electrical Characteristics TA=25°C unless otherwise noted

| Symbol | Parameter | | Test Conditions | Min. | Max. | Units |
|-----------------|-----------------------|----------------|--|----------|----------------------------------|----------------------------|
| V _R | Breakdown Voltage | BAV70 BAV74 | I _R = 100μA I _R = 5.0μA | 75 50 | | V V |
| V _F | Forward Voltage | BAV70 BAV74 | $I_F = 1.0 \text{mA}$ $I_F = 10 \text{mA}$ $I_F = 50 \text{mA}$ $I_F = 150 \text{mA}$ $I_F = 100 \text{mA}$ | | 715 855 1.0 1.25 1.0 | mV mV V V |
| I _R | Reverse Leakage | BAV70 BAV74 | $V_R = 25V, T_A = 150^{\circ}C$ $V_R = 70V$ $V_R = 70V, T_A = 150^{\circ}C$ $V_R = 50V$ $V_R = 50V, T_A = 150^{\circ}C$ | | 60 5.0 100 100 | μΑ μΑ μΑ nA μΑ |
| C _T | Total Capacitance | BAV70 BAV74 | $V_R = 0V$, $f = 1.0MHz$ $V_R = 0V$, $f = 1.0MHz$ | | 1.5 2.0 | pF pF |
| t _{rr} | Reverse Recovery Time | BAV70 BAV74 | $\begin{aligned} &I_F = I_R = 10\text{mA}, \ I_{RR} = 1.0\text{mA}, \\ &R_L = 100\Omega \\ &I_F = I_R = 10\text{mA}, \ I_{RR} = 1.0\text{mA}, \\ &R_L = 100\Omega \end{aligned}$ | | 6.0 4.0 | ns ns |

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